06/03/2017 504396320

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2

EPAS ID: PAT4443017

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Shih-Yi Syu	01/11/2016
Tung-Hsien Hsieh	01/12/2016
Che-Ya Chou	01/11/2016

RECEIVING PARTY DATA

Name:	MEDIATEK INC.
Street Address:	No. 1, Dusing Rd. 1st, Science-Based Industrial Park
City:	Hsin-Chu
State/Country:	TAIWAN

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	15613144

CORRESPONDENCE DATA

Fax Number: (703)997-4517

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent

using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

3027291562 Phone:

Email: Patent.admin.uspto.cr@naipo.com

Correspondent Name: WINSTON HSU

Address Line 1: 5F., NO.389, FUHE RD., YONGHE DIST.,

Address Line 4: **NEW TAIPEI CITY, TAIWAN**

ATTORNEY DOCKET NUMBER:	MTKP2375USA3
NAME OF SUBMITTER:	KATE YEH
SIGNATURE:	/KATE YEH/
DATE SIGNED:	06/03/2017

Total Attachments: 6

source=2869235#page1.tif

source=2869235#page2.tif

source=2869235#page3.tif

source=2869235#page4.tif

source=2869235#page5.tif

REEL: 042585 FRAME: 0089 504396320

PATENT

source=2869235#page6.tif

PATENT REEL: 042585 FRAME: 0090

COMBINE DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT

Title of Invention:

SEMICONDUCTOR DEVICE AND WAFER LEVEL PACKAGE INCLUDING SUCH SEMICONDUCTOR DEVICE

As the below named inventor, I hereby declare that: This declaration is directed to:		
☑ The attached application, or		
☐ United States application number	filed on	, or
□ PCT international application number	filed on	***************************************
The above-identified application was made or authorized	to be made by me.	
I believe that I am the original inventor or an original joint application.	inventor of a claimed invention in the	е
I hereby acknowledge that any willful false statement mad under18 U.S.C. 1001 by fine or imprisonment of not more	le in this declaration is punishable than five (5) years, or both.	
In consideration of the payment by MEDIATEK INC.	having a posta	l address of
No. 1, Dusing Rd. 1st, Science-Based Industria	l Park, Hsin-Chu 300, Taiwan	, R.O.C.
(referred to as "ASSIGNEE"below) to I of the sum of One acknowledged, andfor other good and valuable considerated	Dollar (\$ 1.00), the receipt of which tion.	is hereby
I hereby sell, assign and transfer to ASSIGNEE and the so the entire right, title and interest in and to any and all impro invention as above-identified application and, in and to, all invention by the above application or any continuations, co substitutes, or extensions thereof, and as to Letters Paten	ovements which are disclosed in the Letters Patent to be obtained for sa ontinuation-in-part, divisions, renewa	e aid als
I hereby covenant that no assignment, sale, agreement or entered into which would conflict with this assignment;	encumbrance has been or will be n	nade or
I further covenant that ASSIGNEE will, upon its request, be and documents relating to said invention and said Letters known and accessible to I and will testify as to the same in related thereto and will promptly execute and deliver to AS	Patent and legal equivalents as may any interference. litigation proceed	/ be
representatives any and all papers, instruments or affidavi maintain, issue and enforce said application, said invention equivalents thereof which may be necessary or desirable to N WINTNESS WHEREOF, I have hereunto set hand and	n and said Letters Patent and said to carry out the proposes thereof.	ate of signing)
Note: An application data sheet (PTO/SB/14 or equivalent) nventive entity, must accompany this form. Use this form), including naming the entire for each additional inventor.	

Page 1 of 6

Docket No MTKP2375USA

Inventor: Shih-Yi Syu

Date: 7016 / 1 / 11

Signature: Shik-Yi, Syu

Page 2 of 6

COMBINE DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT

Title of Invention:

SEMICONDUCTOR DEVICE AND WAFER LEVEL PACKAGE INCLUDING SUCH SEMICONDUCTOR DEVICE

As the below named inventor, I here This declaration is directed to:	eby declare that:			
☑ The attached application, or				
☐ United States application nu	ımber	filed o	n	, or
☐ PCT international application	n number	file	d on	
The above-identified application was	s made or authorized to	be made by me.	-	***************************************
I believe that I am the original invent application.	tor or an original joint in	ventor of a claimed	d invention in th	e
I hereby acknowledge that any willfu under18 U.S.C. 1001 by fine or impr	If false statement made risonment of not more th	in this declaration an five (5) years,	is punishable or both.	
In consideration of the payment by	MEDIATEK INC.		having a posta	al address of
No. 1, Dusing Rd. 1st, Science	e-Based Industrial	Park, Hsin-Chu	- ⊢300, Taiwan	, R.O.C.
(referred to as "ASSIGNEE"below) to acknowledged, andfor other good an	o I of the sum of One Dond valuable consideration	ollar (\$ 1.00), the r n.	eceipt of which	is hereby
I hereby sell, assign and transfer to A the entire right, title and interest in ar invention as above-identified applica invention by the above application or substitutes, or extensions thereof, ar	nd to any and all improvition and, in and to, all L r any continuations, con	rements which are etters Patent to be tinuation-in-part d	disclosed in the obtained for salivisions, renew	e aid als
l hereby covenant that no assignmer entered into which would conflict with	nt, sale, agreement or e n this assignment;	ncumbrance has b	een or will be r	made or
I further covenant that ASSIGNEE wi and documents relating to said inven known and accessible to I and will te related thereto and will promptly exec	ition and said Letters Pa stify as to the same in a	atent and legal equ inv interference, lit	uivalents as mag	v he
representatives any and all papers, in maintain, issue and enforce said app equivalents thereof which may be ne N WINTNESS WHEREOF, I have he	olication, said invention a ecessary or desirable to	and said Letters Pa carry out the prop	atent and said oses thereof.	ate of signing)
Note: An application data sheet (PTC nventive entity, must accompany this	D/SB/14 or equivalent), s form. Use this form for	including naming t	he entire	

Page 3 of 6

NPO#MTK-P2375-USA:0 CUST#MTKI-15-106US

F#NPO-P0002E-US1201 DSB0-104U017771

Docket No MTKP2375USA

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: Tung-Hsien Hsieh

Date: 20/6/1//2

Signature: Tung - Hsien, Hsieh

Page 4 of 6

COMBINE DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT

Title of Invention:

SEMICONDUCTOR DEVICE AND WAFER LEVEL PACKAGE INCLUDING SUCH SEMICONDUCTOR DEVICE

As the below named inventor, I here This declaration is directed to:	by declare that:		
☑ The attached application, or			
☐ United States application nu	mber	filed on	, or
☐ PCT international application	number	filed on	***************************************
The above-identified application was	made or authorized to be ma	ade by me.	
I believe that I am the original invente application.	or or an original joint inventor	of a claimed invention in th	e
I hereby acknowledge that any willful false statement made in this declaration is punishable under18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.			
In consideration of the payment by	MEDIATEK INC.	having a posta	al address of
No. 1, Dusing Rd. 1st, Science	e-Based Industrial Park,	Hsin-Chu 300, Taiwan	, R.O.C.
(referred to as "ASSIGNEE"below) to acknowledged, andfor other good an	o I of the sum of One Dollar (\$ d valuable consideration.	1.00), the receipt of which	is hereby
I hereby sell, assign and transfer to A the entire right, title and interest in an invention as above-identified applicat invention by the above application or substitutes, or extensions thereof, an	nd to any and all improvement tion and, in and to, all Letters any continuations, continuation	is which are disclosed in the Patent to be obtained for sa on-in-part, divisions, renew	e aid als
hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;			
further covenant that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to I and will testify as to the same in any interference, litigation proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal			
epresentatives any and all papers, ir maintain, issue and enforce said appl equivalents thereof which may be ned N WINTNESS WHEREOF, I have he	lication, said invention and sa	id Letters Patent and said out the proposes thereof.	ate of signing)
Note: An application data sheet (PTC nventive entity, must accompany this	n/SB/14 or equivalent), includions form. Use this form for <u>each</u>	ng naming the entire additional inventor.	

Page 5 of 6

NPO#MTK-P2375-USA:0 CUST#MTKI-15-106US

F#NPO-P0002E-US1201 DSB0-104U017771

Docket No MTKP2375USA

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor:

Che-Ya Chou

Date:

01/11/2016

Signature:

Che-la, Chou

Page 6 of 6

F#NPO-P0002E-US1201 DSB0-104U017771

PATENT REEL: 042585 FRAME: 0096